506467347 01/25/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
XINGFEI MAO	01/22/2021

RECEIVING PARTY DATA

Name:	BEIJING NAURA MICROELECTRONICS EQUIPMENT CO., LTD.	
Street Address:	NO.8 WENCHANG AVENUE	
Internal Address:	BEIJING ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA	
City:	BEIJING	
State/Country:	CHINA	
Postal Code:	100176	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17263078

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NAME OF SUBMITTER:	RAINEE LOCKE
SIGNATURE:	/Rainee Locke/
DATE SIGNED:	01/25/2021

Total Attachments: 2

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PATENT 506467347 REEL: 055023 FRAME: 0104

ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

LIFT THIMBLE SYSTEM, REACTION CHAMBER, AND SEMICONDUCTOR PROCESSING EQUIPMENT

for which I/We executed an application for United States	Ladiana Prataut
national stage in the United States of nor a grant	cetters Patent concurrently herewith, as a
national stage in the United States of PCT Application N	 PCT/CN2019/098370, or filed an application
for United States Letters Patent on(Applicati	on No
A to the second	J, and

WHEREAS, BEIJING NAURA MICROELECTRONICS EQUIPMENT CO. LTD., a limited company of P.R. China, whose post office address is No.8 Wenchang Avenue, Beijing Economic-Technological Development Area, Beijing 100176, P.R. China (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys empowered in the Power of Attorney in this application, to insert here in parentheses (Application No. 17/263,078, filed Ian 25, 2021) the filing date and application number of said application when known.

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IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inve	entor:
Name:	Xingfei MAO
Signature:	*XX
Date:	2021.1.22